

METHOD OF WAFER PROCESSING WITH EDGE SEED LAYER
REMOVAL

Basol et al.

Appl. No.: 10/782,697

Atty Docket: ASMNUT.031CP1

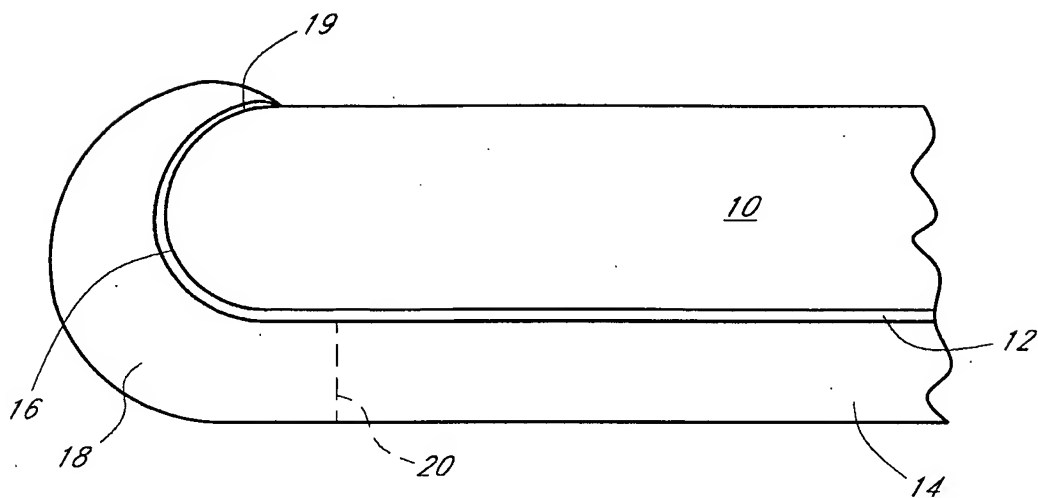


FIG. 1

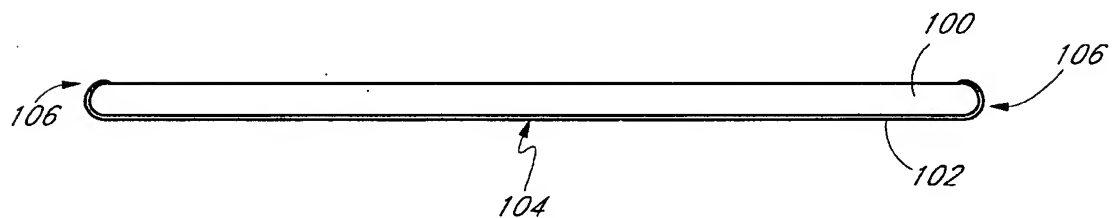


FIG. 2A

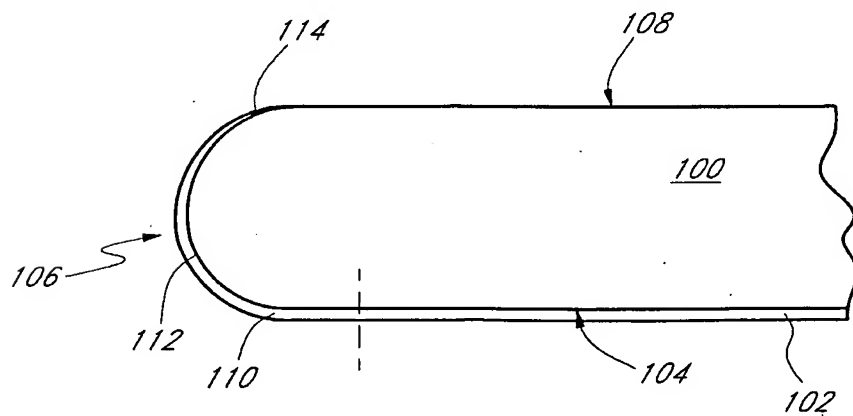


FIG. 2B

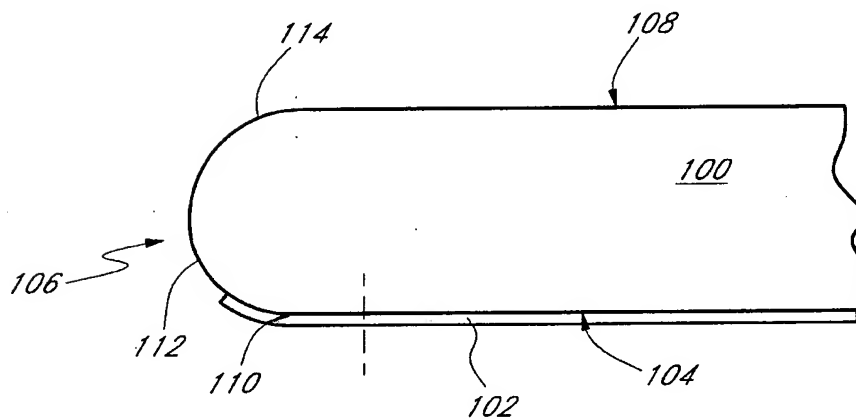


FIG. 3

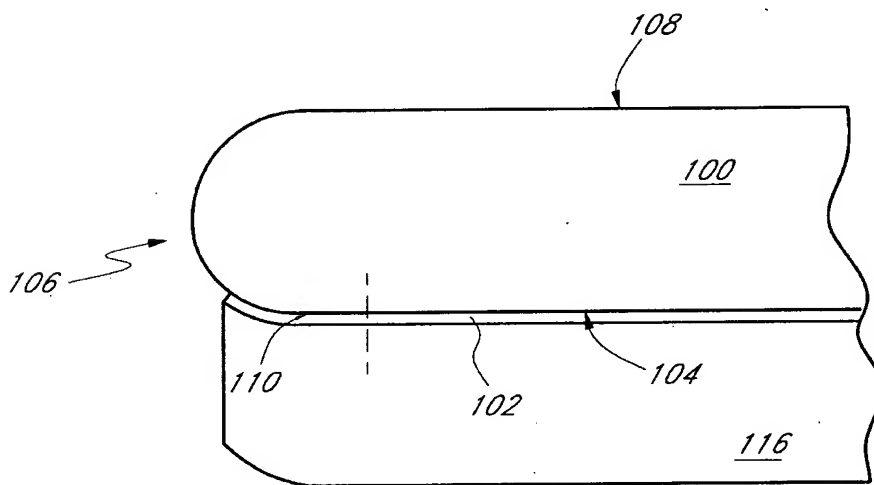


FIG. 4

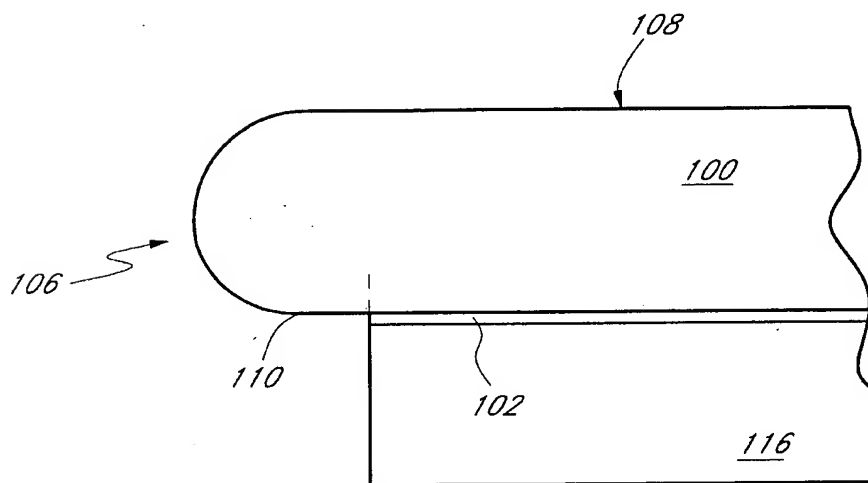


FIG. 5

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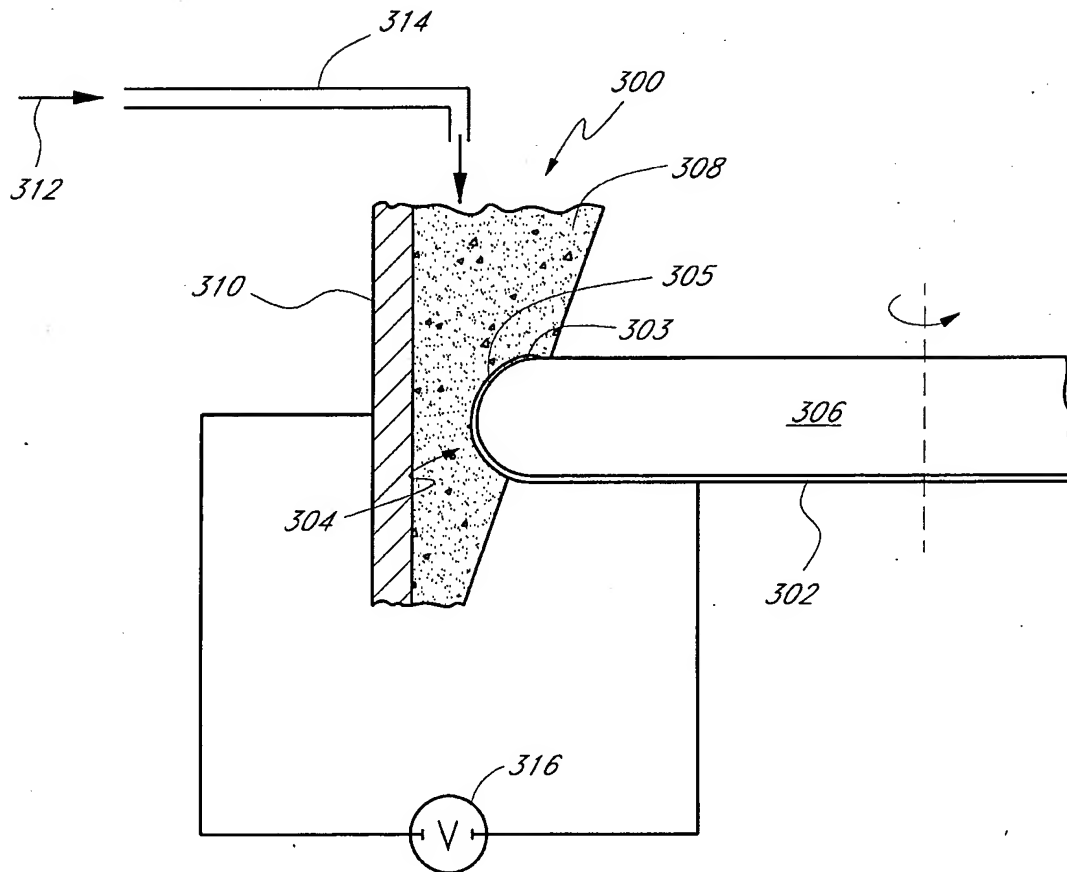


FIG. 8